



LINXENS

CONNECTING YOU TO SUCCESS

SMART-SL PRODUCT FAMILY

SMART-SL HF & SMART-SL UHF



The SMART-SL product family is aimed at providing card manufacturers and security printers with a pioneering product range to meet tomorrow's requirements for high-security contactless identity documents.

Manufactured with patented wire-embedding technology on different substrates, the SMART-SL product portfolio is available in various form factors and sizes. The products are available in HF and UHF operating frequencies and can optionally be equipped with the highly-sophisticated Anti-Crack feature [AC].

Able to withstand critical stress, including around the chip area, the homogeneous flat inlay surface provides the best protection against micro cracks, particularly in brittle material such as polycarbonate.

Furthermore, the outstanding product thinness enables easy integration of enhanced security features in ID cards or plastic data pages for e-passports, providing card manufacturers and security printers with enhanced flexibility and optimization of production processes.

Overview

Operating Frequency

13.56 MHz (HF)
860-960 MHz (UHF)

Operating Temperature

-25°C to +50°C

Integrated Circuit (IC)

ICs from leading suppliers

Material

PC, PVC, PET-G, Teslin®, Composite

International Standards

- ISO 14443
- ISO 15693
- ISO 18000-6C

Application Area

- eID Documents
- ePassport
- eDriver's License
- eResident Permit
- Border Crossing

Features

- SMART-AC [Anti-Crack]

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Product	Operating Frequency	Sheet format	Thickness	Available IC
SMART-SL HF	13.56 MHz	Max. 580 x 705 mm	approx. 300µm	Infineon, NXP, ST, Samsung
SMART-SL HF	860 – 960 MHz	Max. 580 x 705 mm	approx. 300µm	Alien, Impinj

Additional memory, protocol and product configurations are available upon request.